



Material Content Data Sheet



Sales Product Name		SAK-XC167CI-16F40F BB		Issued		29. August 2013		
MA#		MA000964754						
Package		PG-TQFP-144-7		Weight*		1403.11 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	28.260	2.01	2.01	20141	20141
leadframe	non noble metal	magnesium	7439-95-4	0.529	0.04		377	
	inorganic material	silicon	7440-21-3	2.293	0.16		1634	
	non noble metal	nickel	7440-02-0	10.581	0.75		7541	
wire	non noble metal	copper	7440-50-8	339.310	24.18	25.13	241827	251379
	noble metal	gold	7440-57-5	4.158	0.30	0.30	2963	2963
	encapsulation	organic material	carbon black	1333-86-4	4.995	0.36		3560
encapsulation	plastics	epoxy resin	-	134.876	9.61		96126	
	inorganic material	silicondioxide	60676-86-0	859.210	61.24	71.21	612360	712046
leadfinish	non noble metal	tin	7440-31-5	8.638	0.62	0.62	6156	6156
plating	noble metal	silver	7440-22-4	4.833	0.34	0.34	3445	3445
glue	plastics	epoxy resin	-	1.086	0.08		774	
	noble metal	silver	7440-22-4	4.344	0.31	0.39	3096	3870
*deviation	< 10%				Sum in total:	100,00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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